ABSTRACT

METHODS FOR DESIGNING SOLDER MASKS WITH RECESSED AREAS AND CARRIERS WITH PROTRUDING CONTACTS, AND FOR FORMING ASSEMBLIES INCLUDING THE SOLDER MASKS OR CARRIERS

A method for designing a carrier includes configuring at least one die attach location and one or more terminals that protrude from a surface of the carrier so as to prevent adhesive material from contaminating connection surfaces thereof. A method for designing a solder mask includes configuring a device securing region to be positioned over at least a portion of a die support location of a carrier. Dams of the solder mask are positionable laterally adjacent to at least portions of the peripheries of corresponding terminals of the carrier. The carrier and solder mask may each be designed to include one or more recessed areas that laterally surround at least portions of their die attach location and device securing region, respectively, to receive some of the excess adhesive. Methods for forming assemblies that include one or both of the carrier and solder mask are also disclosed.

[FIG. 10]